

Abstract

To reduce residual stress generated on a protective tape at a time of application of the protective tape to a semiconductor wafer, provided is an application apparatus (1) for applying a protective tape (PT) to a semiconductor wafer (W), including: a tape conveyance mechanism (2) configured to convey the protective tape (PT) temporarily applied to a base material (BM) to a peeling position; a tape holding body (30) capable of holding the protective tape (PT); a holding-body moving mechanism (31) configured to move the tape holding body (30) to the peeling position; and a peeling mechanism (4) configured to peel the base material (BM) from the protective tape (PT) held by the tape holding body (30) at the peeling position.